Hi all,

Here are the minutes of today;'s meeting.

o Taiwan Assembly <Cheng-Wei>

- **Cheng-Wei** will make a link from INTT wiki to the new ladder classification code.

- **Itaru** contact with FVTX crews which FPGA compiler version they used to compile the ROC codes.

- **Cheng-Wei** will initiate e-mail discussion with NTU FPGA coder and Takashi regarding the phase shift development.

- **Cheng-Wei** procured DP460 glue. Since he won't visit to NTU at least until June 12th, he will investigate the cooling tube issue in NCU using newly purchased DP460 for the time being.

o Report from the review <Rachid>

- Postpone the readout review from June 15th to July 15h. Schedule review will be postponed to end of July accordingly.

- **Genki** will develop the individual chip reset function for the review.

- **Wei** takes care of the ladder classification.

- **Rachid** proceeds assembly for bulk chip assembly then on HDIs before mounting silicons. This is the most efficient way to proceed.

o Stave preparation for batch-3 <Itaru>

- The outer diameter for the carbon tube edges are optimized to be 2.85mm which leaves 0.05mm space for the glue. The carbon tube thickness will be 0.4mm at the both edge instead of originally designed 0.5mm. However, the strength is still sufficiently rigid as far as Itaru checked.

- Itaru forwarded Rob's instruction to Asuka and they will try to follow Rob's method and try to survive 1Nm torque test.

Regards,

-itaru

On 2021/06/02 22:52, Itaru Nakagawa wrote:

Dear all,

We'll have weekly INTT meeting on

June 2nd Wednesday, 8PM in Eastern time = June 3rd Thursday 9AM in Japan = 8AM in Taiwan

*indico

https://indico.bnl.gov/event/12049/

*Zoom

https://zoom.us/j/92149923535

Best regards,

-itaru

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